

Appl. No. 10/710,580
Amdt. dated August 31, 2005
Reply to Office action of August 02, 2005

REMARKS/ARGUMENTS

Examiner:

5 Claims 1, 3, 9, 11 are rejected under 35 U.S.C. 102(b) as being anticipated by
Sletten et al., U.S. patent No. 6,271,792. Claims 2 and 10 are rejected under 35 U.S.C.
103(a) as being unpatentable over Sletten et al., U.S. patent No. 6,271,792 in view of
O'Neill, Jr., U.S. Patent No. 5,969,681. Claims 4-8, 12, 14-17, and 19-20 are rejected
under 35 U.S.C. 103(a) as being unpatentable over Sletten et al., U.S. patent No.
6,271,792 in view of Tillery et al., U.S. Pub. No. 2004/0150561. Claim 18 is rejected
10 under 35 U.S.C. 103(a) as being unpatentable over Sletten et al., U.S. patent No.
6,271,792 in view of Tillery et al., U.S. Pub. No. 2004/0150561 and further in view of
O'Neill, Jr., U.S. Patent No. 5,969,681.

Response:

15 Point #1 of the Detailed Action on Page 2 of this Office action refers to a request
for continued examination of this application dated 03/17/2005 and that claims 1-3, 5,
7-13, 15, and 17-20 are pending in this application. The Applicant has no knowledge of
any RCE dated 03/17/2005 and states for the record that this Office action dated
08/02/2005 is the first response on merit for this application filed 07/22/2004. It is
20 therefore assumed that all claims 1-20 in the originally filed application are still pending
in this application. The balance of this response to the Office action is formulated under
this assumption. Should this assumption prove to be incorrect, the Applicant respectfully
requests detailed information concerning when and how claims 4, 6, 14, and 16 of the
originally filed specification were removed from consideration.

25 The present application utilizes a first priming layer on the top surface of the
dielectric layer and a second priming layer on the bottom surface of the dielectric layer

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as is claimed in each independent claim of the present application. Adhesive layers respectively attach the radiating element and the ground plate to the first and second priming layers. "The polymeric surfactants priming layers 205 effectively roughen and prepare the surfaces of the dielectric layer 115 for better adhesion to the adhesive layers 119 in cold temperature environments" (Present Application, Paragraph [0029]). Thus the claimed priming layers are an essential part of the claimed embodiment, and provide tangible, real-world benefits by solving the separation problem discussed in Paragraph [0027].

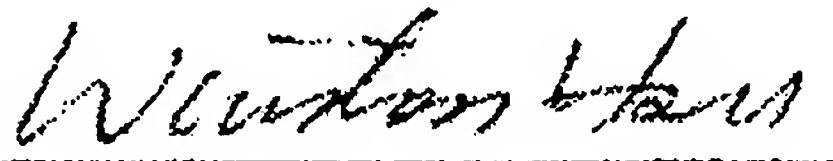
The Applicant is unable to locate any teachings or suggestion in any of the cited prior art of utilizing priming layers as claimed. Instead, Sletten et al. teach that the adhesive material 202, 203 "bonds the copper 201 and 204 to the dielectric PMP material 205" (Col.3, lines 55-57). There is no priming layer utilized. Priming layers are not shown in the drawings, mentioned or suggested in the text, nor specifically pointed out by the Examiner, and it is certainly not inherent to utilize them.

Concerning claim 9, the Examiner refers to a structure of an antenna and the cited references do not teach or suggest all of the steps in the present application. Because claim 9 is not a product-by-process claim and certainly recites serial steps of a method of manufacturing an antenna, claim 9 should not be anticipated by a structure description.

As such, it is believed that the known prior art, alone or in combination, does not anticipate every limitation of claims 1, 9, and 17 and respectfully requests reconsideration and allowance of independent claims 1, 9, and 17. Although it is also believed that limitations found in several of the dependent claims are also not taught in the prior art, because their allowability ultimately depends upon the allowability of their respective base claim, reconsideration and allowance of claims 2-8, 10-16, and 18-20 is also respectfully requested.

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Sincerely yours,



Date: August 31, 2005

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